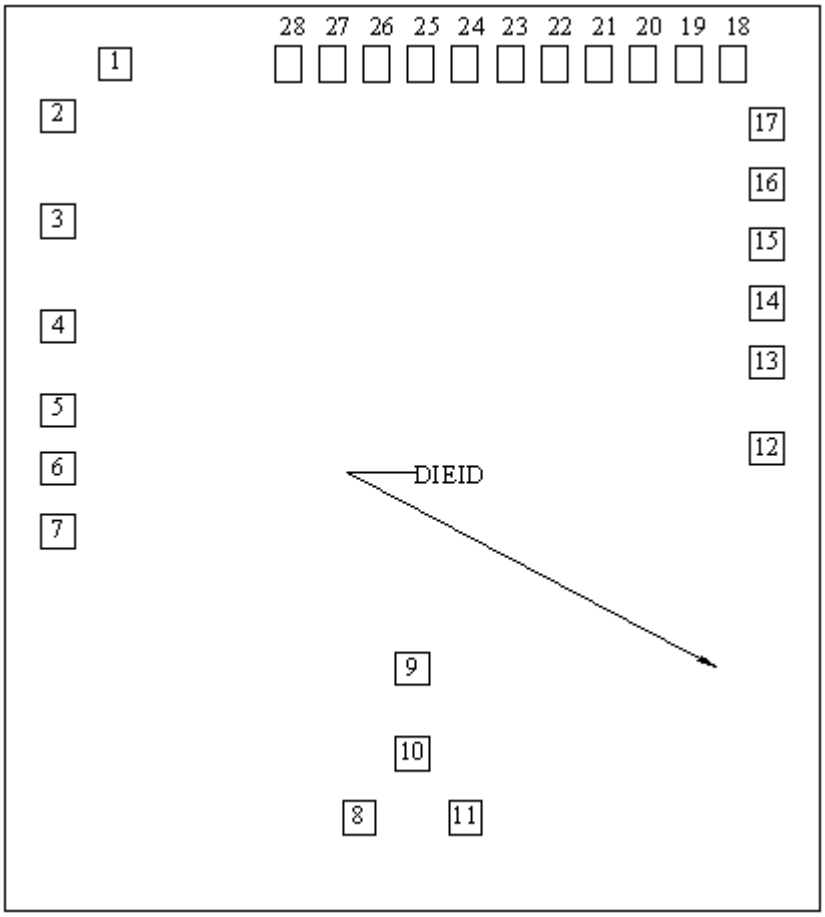
LM5025 MDC MWC
ACTIVE CLAMP VOLTAGE MODE PWM CONTROLLER

November 02,2007

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM5025A	Bond Pad Opening Size (min)	91μm x 91μm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	2286μm x 2540μm 90.0mils x 100.0mils	Back Side Connection	Floating
Thickness	254μm Nominal		
Min Pitch	167μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
VIN	1	-834	1109	91	x	91
RAMP	2	-996	962	91	x	91
CS1	3	-996	665	91	x	91
CS2	4	-996	368	91	x	91
TIME	5	-996	136	91	x	91
REF	6	-996	-31	91	x	91
VCC	7	-996	-206	91	x	91
OUT_A	8	-150	-1010	91	x	91
VCC	9	-1	-593	91	x	91
PGND	10	-1	-831	91	x	91
OUT_B	11	148	-1010	91	x	91
AGND	12	995	26	91	x	91
SS	13	995	267	91	x	91
COMP	14	995	435	91	x	91
RT	15	995	602	91	x	91
SYNC	16	995	770	91	x	91
UVLO	17	995	937	91	x	91
NC	18	898	1109	73	x	100
NC	19	773	1109	73	x	100
NC	20	648	1109	73	x	100
NC	21	523	1109	73	x	100
NC	22	398	1109	73	x	100
NC	23	273	1109	73	x	100
NC	24	148	1109	73	x	100
NC	25	23	1109	73	x	100
NC	26	-102	1109	73	x	100
NC	27	-227	1109	73	x	100
NC	28	-352	1109	73	x	100

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Notes

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